Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claims 1-25 (canceled)

Claim 26 (Currently amended): A test apparatus for testing ~~an electronic device~~ semiconductor dies, said apparatus comprising:

a substrate; and

a plurality of microelectronic probes, each said probe comprising:

a contact tip disposed to make a temporary, pressure based connection with a terminal of ~~said electronic device~~ one of said dies during testing of said ~~electronic device~~ dies;

a base secured to said substrate; and

a body disposed at least in part away from said substrate and configured to flex and exert a counter force while said contact tip is pressed against said terminal of said ~~electronic device~~ one of said dies,

wherein said body is attached to said base and said tip is attached to said body,

said tip comprises substantially ~~palladium or~~ a palladium cobalt alloy, and

said body comprises substantially a spring material that does not comprise a substantial amount of the palladium cobalt alloy.

Claim 27-32 (Canceled)

Claim 33 (Previously presented): The test apparatus of claim 26, wherein said tip is integrally formed with said body.

Claim 34 (Canceled)

Claim 35 (Withdrawn): The test apparatus of claim 26, wherein said base and said body are integrally formed.

Claim 36 (Previously presented): The test apparatus of claim 26, wherein said body comprises a beam that is structurally distinct from said base.

Claim 37-40 (Canceled)

Claim 41 (Previously presented): The test apparatus of claim 26, wherein said test apparatus is a probe card assembly.

Claim 42 (Currently amended): A test apparatus for testing ~~an electronic device~~ a plurality of semiconductor dies, said test apparatus comprising:

a substrate; and

a plurality of microelectronic probes attached to said substrate, each said probe comprising:

a contact tip disposed to make a temporary, pressure based electrical connection with a terminal of ~~said electronic device~~ one of said dies to be tested, wherein said contact tip comprises substantially ~~palladium or~~ a palladium cobalt alloy, and

a spring-like body configured to flex and exert a counter force in response to said contact tip being pressed against said terminal of said ~~electronic device~~ one of said dies, wherein said body comprises a resilient material and does not comprise a substantial amount of said palladium cobalt alloy.

Claims 43-47 (Canceled)

Claim 48 (Previously presented): The test apparatus of claim 42, wherein said test apparatus is a probe card assembly.

Claims 49-72 (Canceled)

Claim 73 (Previously presented): The test apparatus of claim 26, wherein said body and said base are distinct structures.

Claim 74 (Previously presented): The test apparatus of claim 26, wherein said body and said tip are distinct structures.

Claim 75 (Previously presented): The test apparatus of claim 74, wherein said body and said base are distinct structures.

Claim 76 (Currently amended): The test apparatus of claim 26, wherein each probe is configured to contact one of said terminals of said ~~electronic device~~ dies such that no two probes contact a same terminal of said ~~electronic device~~ dies.

Claim 77 (Currently amended): The test apparatus of claim 76, wherein said base is attached to said body at a first end of said body and said tip is attached to said body at a second end of said body, and said second end of said body is moveable such that said second end of said body deflects upon contact with a terminal of said ~~electronic device~~ dies.

Claim 78 (Previously presented): The test apparatus of claim 26, wherein said palladium cobalt alloy is electroplated.

Claim 79 (Previously presented): The test apparatus of claim 42, wherein each said probe further comprises a post attached to a terminal on said substrate , said body connecting said post and said tip.

Claim 80 (Previously presented): The test apparatus of claim 79, wherein said post and said body are distinct structures attached one to another.

Claim 81 (Previously presented): The test apparatus of claim 80, wherein said tip and said body are distinct structures attached to one another.

Claim 82 (Previously presented): The test apparatus of claim 79, wherein said tip and said body are distinct structures attached to one another.

Claim 83 (Currently amended): The test apparatus of claim 79, wherein each probe is configured to contact one of said terminals of said ~~electronic device~~ dies such that no two probes contact a same terminal of said ~~electronic device~~ dies.

Claim 84 (Currently amended): The test apparatus of claim 79, wherein said post is attached to said body at a first end of said body and said tip is attached to said body at a second end of said body, and said second end of said body is moveable such that said second end of said body deflects upon contact with a terminal of said ~~electronic device~~ dies.

Claim 85 (Currently amended): The test apparatus of claim 42, wherein said palladium cobalt alloy is electroplated.

Claim 86 (Canceled)

Claim 87 (Currently amended): The test apparatus of claim 26, wherein said contact tips of said probes are disposed to contact terminals of said ~~electronic device~~ dies having a pitch of less than five mils spacing between adjacent ones of said terminals.

Claim 88 (Canceled)

Claim 89 (Currently amended): The test apparatus of ~~claim 88~~ claim 89, wherein [[said] tips of said probes are disposed to make temporary contact simultaneously with a plurality of terminals of a plurality of said semiconductor dies.

Claim 90 (Previously presented): The test apparatus of claim 89, wherein said plurality of dies compose an unsingulated semiconductor wafer.

Claim 91 (Currently amended): The test apparatus of claim 88, wherein said terminals are bond pads of said ~~semiconductor die~~ semiconductor dies.

Claim 92 (Previously presented): The test apparatus of claim 26, wherein said terminal is flat.

Claim 93 (Canceled)

Claim 94 (Currently amended): ~~The test apparatus of claim 42,~~ A test apparatus for testing an electronic device, said test apparatus comprising:

a substrate; and

a plurality of probes attached to said substrate, each said probe comprising:

a contact tip disposed to make a temporary, pressure based electrical connection with a terminal of said electronic device to be tested, wherein said contact tip comprises substantially palladium or a palladium alloy, and

a spring-like body configured to flex and exert a counter force in response to said contact tip being pressed against said terminal of said electronic device, wherein said body comprises a resilient material and does not comprise a substantial amount of palladium,

wherein said contact tips of said probes are disposed to contact terminals of said electronic device having a pitch of less than five mils spacing between adjacent ones of said terminals.

Claim 95 (Currently amended) ~~The test apparatus of claim 42,~~ A test apparatus for testing an electronic device, said test apparatus comprising:

a substrate; and

a plurality of probes attached to said substrate, each said probe comprising:

a contact tip disposed to make a temporary, pressure based electrical connection with a terminal of said electronic device to be tested, wherein said contact tip comprises substantially palladium or a palladium alloy, and

a spring-like body configured to flex and exert a counter force in response to said contact tip being pressed against said terminal of said electronic device, wherein said body comprises a resilient material and does not comprise a substantial amount of palladium,

wherein said electronic device comprises a semiconductor die, and said contact tips of said probes are disposed to make temporary contact with a plurality of terminals of said semiconductor die.

Claim 96 (Currently amended): The test apparatus of claim 95, wherein [[said]] tips of said probes are disposed to make temporary contact simultaneously with a plurality of terminals of a plurality of said semiconductor dies.

Claim 97 (Previously presented): The test apparatus of claim 96, wherein said plurality of dies compose an unsingulated semiconductor wafer.

Claim 98 (Previously presented): The test apparatus of claim 95, wherein said terminals are bond pads of said semiconductor die.

Claim 99 (Currently amended): ~~The test apparatus of claim 42,~~ A test apparatus for testing an electronic device, said test apparatus comprising:

a substrate; and

a plurality of probes attached to said substrate, each said probe comprising:

a contact tip disposed to make a temporary, pressure based electrical connection with a terminal of said electronic device to be tested, wherein said contact tip comprises substantially palladium or a palladium alloy, and

a spring-like body configured to flex and exert a counter force in response to said contact tip being pressed against said terminal of said electronic device, wherein said body comprises a resilient material and does not comprise a substantial amount of palladium,

wherein said terminal is flat.